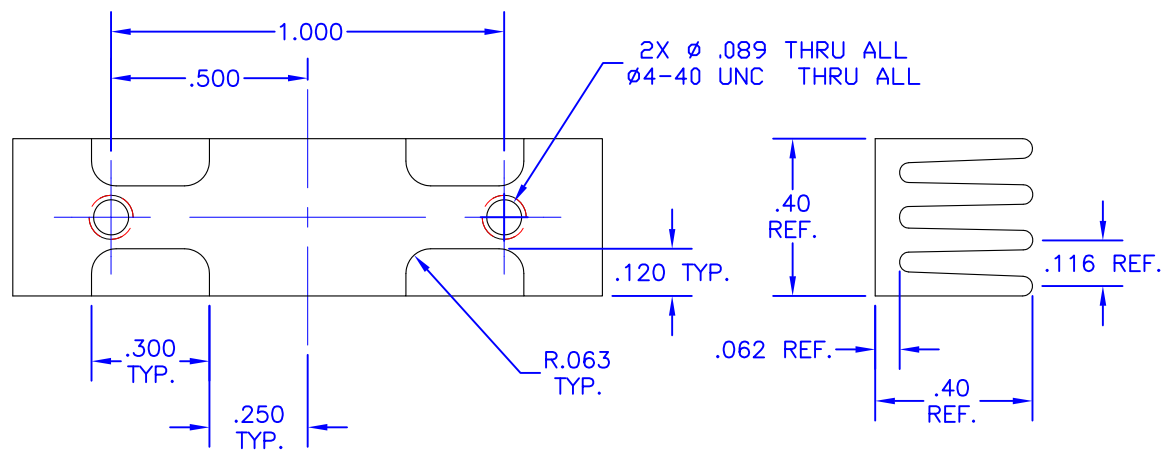
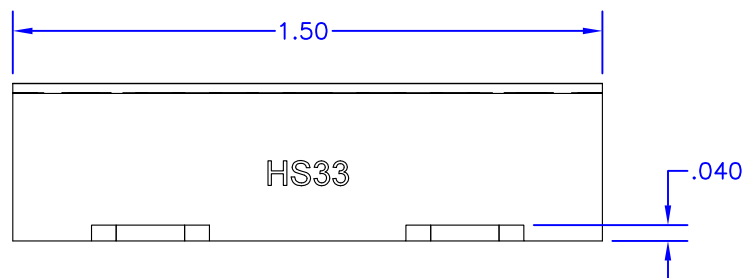
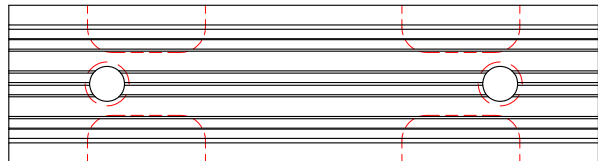


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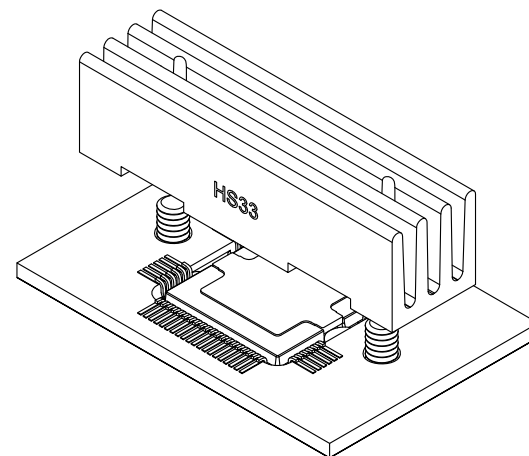
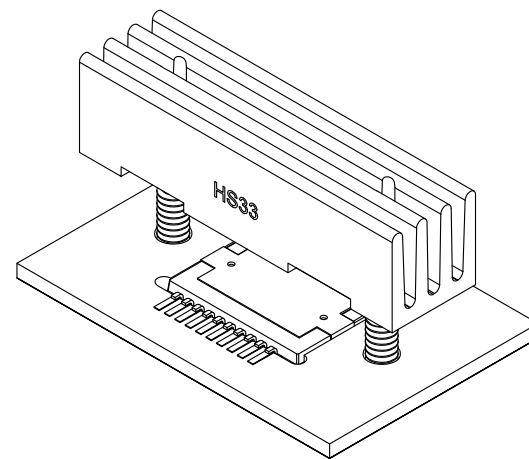
3

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1



INVERTED THROUGH CIRCUIT BOARD
MOUNTING WITH HEAT SINK
(Patent Pending)



NOTES:

1. Unless otherwise noted, all dimensions are in inches.
2. Break all sharp edges, de-burr & remove loose chips.
3. Material: 6063-T5 aluminum alloy. Make from Aavid extrusion 70920
4. Mark with contrasting ink as shown, if specified by P.O.
5. Approximate Weight: 0.22 oz [6.3g]

TOLERANCES - UNLESS
OTHERWISE SPECIFIED
.XX = $\pm .05$ [.002]
.XXX = $\pm .005$ [.0002]
ANG. = $\pm 2^\circ$



TITLE: **DK & HQ PACKAGE HEATSINK**
SUBJECT: **MECHANICAL DRAWING**
ENGINEER: **D-M** DRAWN BY: **P.ECK** DCA: **12436** SHL OF **1 1**

MODEL: **HS33**
FILENAME: **HS33** REV: **B** DATE: **14NOV12**

4

3

2

1